

HiPerFET™

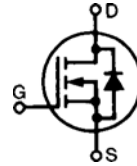
Power MOSFETs Q Class

IXFH/IXFT12N100Q
IXFH/IXFT10N100Q

N-Channel Enhancement Mode
Avalanche Rated
Low Q_g , High dv/dt

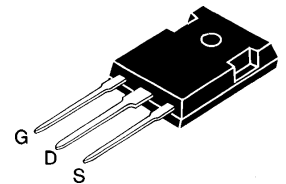
| V_{DSS} | I_{D25} | $R_{DS(on)}$ |
|-----------|-----------|---------------|
| 1000 V | 12 A | 1.05 Ω |
| 1000 V | 10 A | 1.20 Ω |

$$t_{rr} \leq 250 \text{ ns}$$

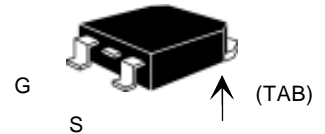


| Symbol | Test Conditions | Maximum Ratings | |
|-----------|---|-----------------|------------------|
| V_{DSS} | $T_J = 25^\circ\text{C}$ to 150°C | 1000 | V |
| V_{DGR} | $T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1 \text{ M}\Omega$ | 1000 | V |
| V_{GS} | Continuous | ± 20 | V |
| V_{GSM} | Transient | ± 30 | V |
| I_{D25} | $T_C = 25^\circ\text{C}$ | 12N100Q | 12 A |
| | | 10N100Q | 10 A |
| I_{DM} | $T_C = 25^\circ\text{C}$, pulse width limited by T_{JM} | 12N100Q | 48 A |
| | | 10N100Q | 40 A |
| I_{AR} | $T_C = 25^\circ\text{C}$ | 12N100Q | 12 A |
| | | 10N100Q | 10 A |
| E_{AR} | $T_C = 25^\circ\text{C}$ | 30 | mJ |
| dv/dt | $I_S \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2 \Omega$ | 5 | V/ns |
| P_D | $T_C = 25^\circ\text{C}$ | 300 | W |
| T_J | | -55 ... +150 | $^\circ\text{C}$ |
| T_{JM} | | 150 | $^\circ\text{C}$ |
| T_{stg} | | -55 ... +150 | $^\circ\text{C}$ |
| T_L | 1.6 mm (0.063 in) from case for 10 s | 300 | $^\circ\text{C}$ |
| M_d | Mounting torque | 1.13/10 | Nm/lb.in. |
| Weight | | TO-247 AD | 6 g |
| | | TO-268 | 4 g |

TO-247 AD (IXFH)



TO-268 (D3) (IXFT)



G = Gate D = Drain
S = Source TAB = Drain

| Symbol | Test Conditions | Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified) | | |
|--------------|---|---|------|----------------------|
| | | min. | typ. | max. |
| V_{DSS} | $V_{GS} = 0 \text{ V}$, $I_D = 3 \text{ mA}$ | 1000 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 4 \text{ mA}$ | 2.5 | | 5.5 V |
| I_{GSS} | $V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$ | | | $\pm 100 \text{ nA}$ |
| I_{DSS} | $V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0 \text{ V}$ | $T_J = 25^\circ\text{C}$ | | 50 μA |
| | | $T_J = 125^\circ\text{C}$ | | 1 mA |
| $R_{DS(on)}$ | $V_{GS} = 10 \text{ V}$, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2\%$ | 12N100Q | | 1.05 Ω |
| | | 10N100Q | | 1.20 Ω |

Features

- IXYS advanced low Q_g process
- Low gate charge and capacitances
 - easier to drive
 - faster switching
- International standard packages
- Low $R_{DS(on)}$
- Unclamped Inductive Switching (UIS) rated
- Molding epoxies meet UL 94 V-0 flammability classification

Advantages

- Easy to mount
- Space savings
- High power density

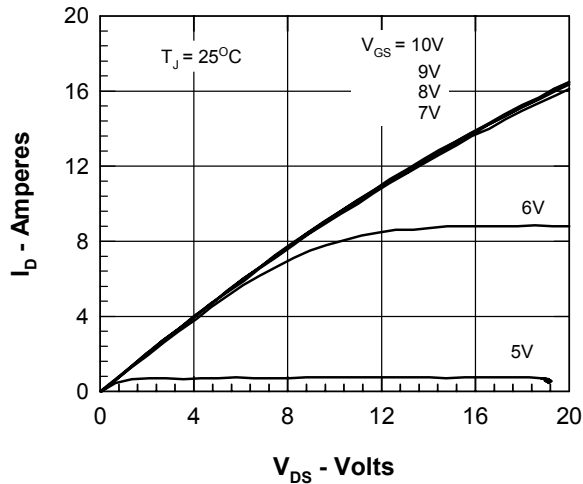


Figure 1. Output Characteristics at 25°C

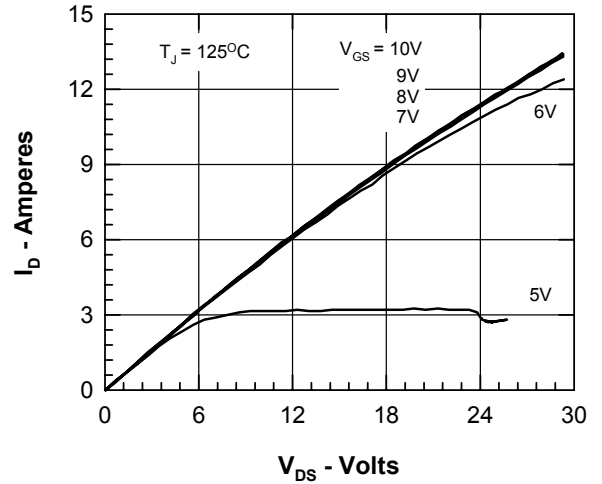


Figure 2. Output Characteristics at 125°C

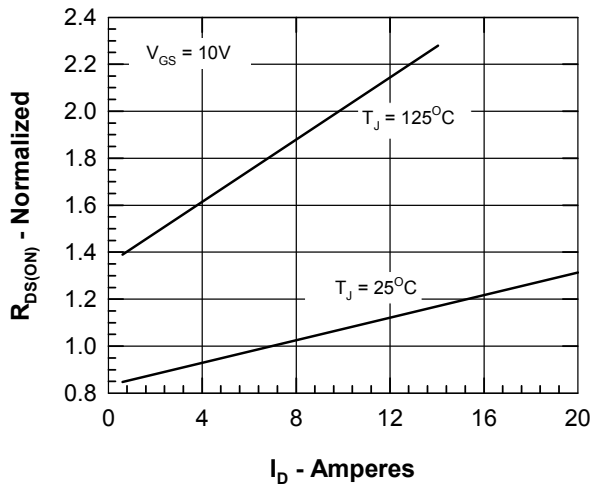


Figure 3. $R_{DS(on)}$ normalized to value at $I_D = 12A$

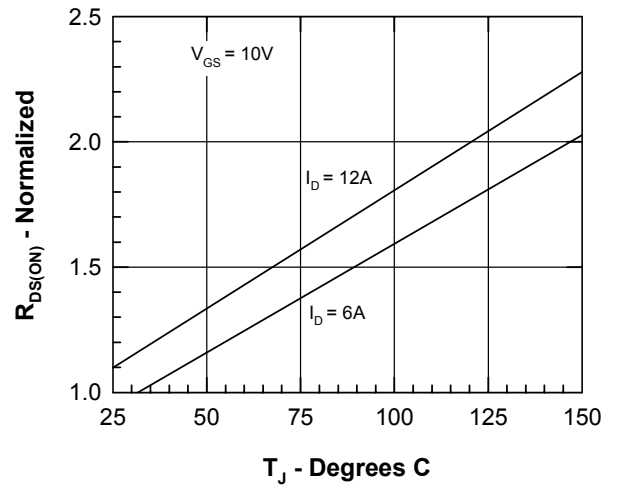


Figure 4. $R_{DS(on)}$ normalized to value at $I_D = 12A$

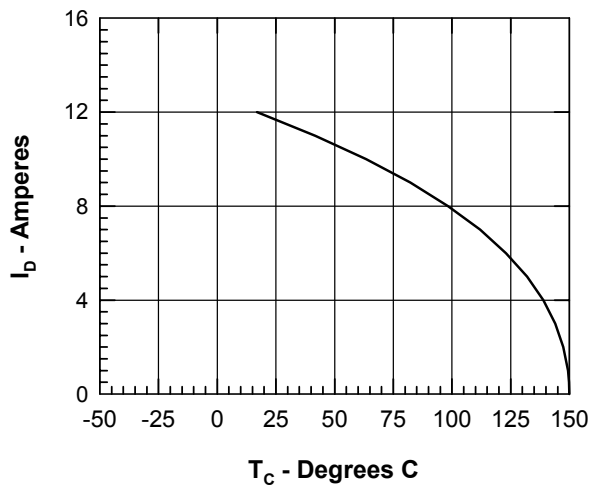


Figure 5. Drain Current vs. Case Temperature

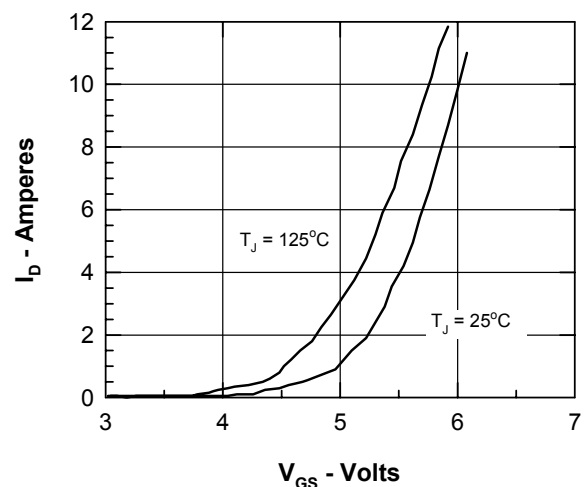


Figure 6. Admittance Curves

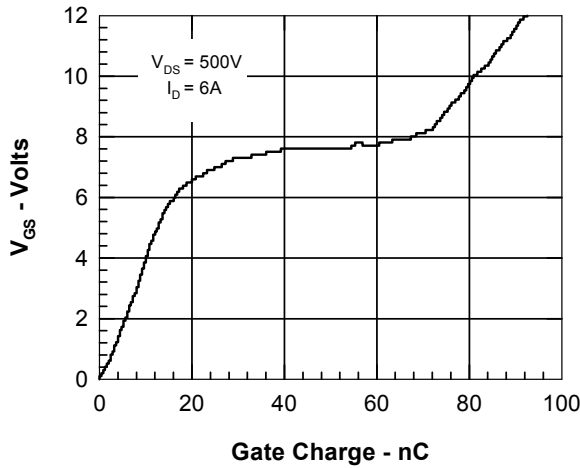


Figure 7. Gate Charge

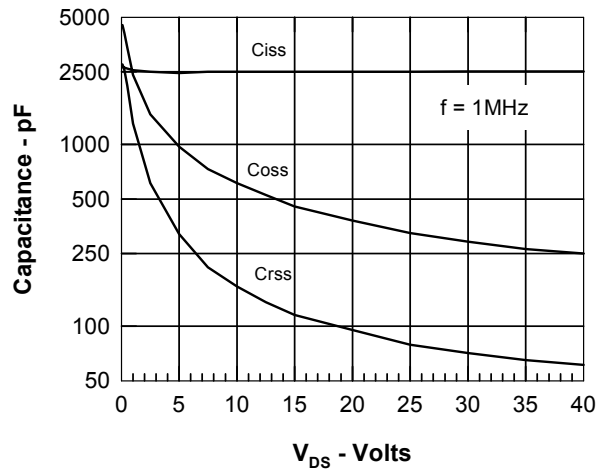


Figure 8. Capacitance Curves

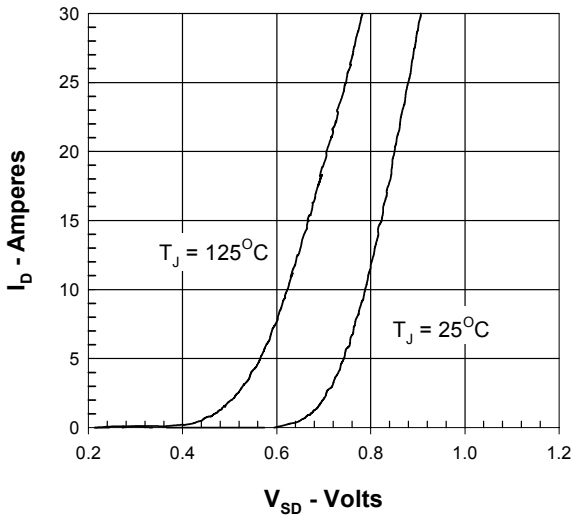


Figure 9. Source Current vs. Source to Drain Voltage

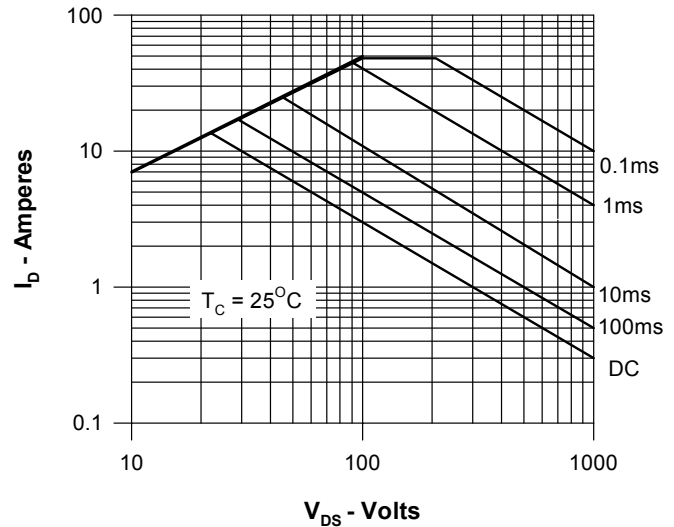


Figure 10. Forward Bias Safe Operating Area

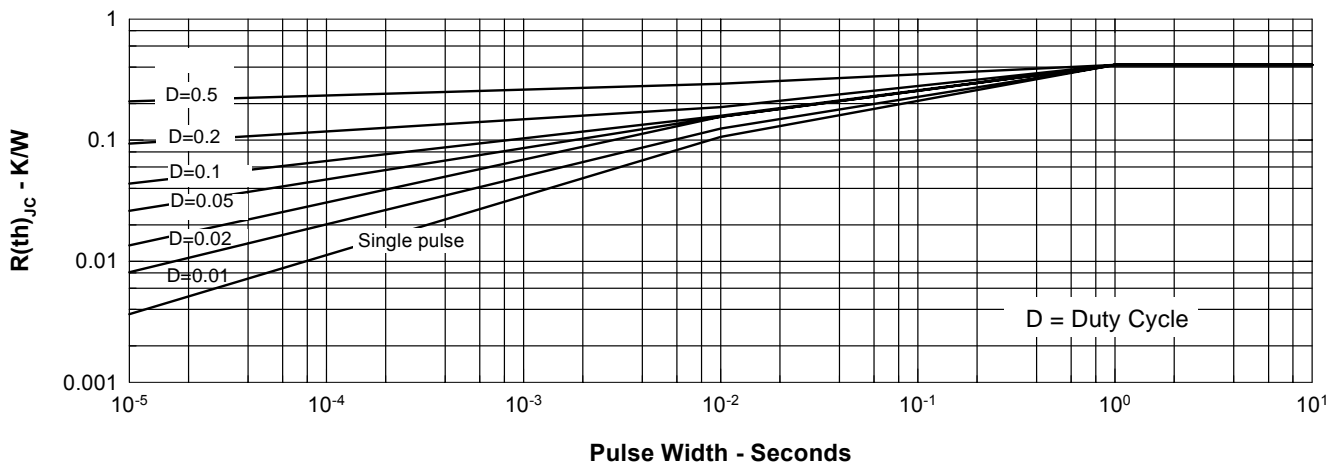


Figure 11. Transient Thermal Resistance

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

| | | | | | | |
|-----------|-----------|-----------|-----------|-----------|-----------|-------------|
| 4,835,592 | 4,881,106 | 5,017,508 | 5,049,961 | 5,187,117 | 5,486,715 | 6,306,728B1 |
| 4,850,072 | 4,931,844 | 5,034,796 | 5,063,307 | 5,237,481 | 5,381,025 | |

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